

date 03/01/2024

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# MODEL: HSB32-232318 | DESCRIPTION: HEAT SINK

#### **FEATURES**

- BGA design
- · aluminum alloy
- · black anodized finish





#### **MODEL** thermal resistance<sup>1</sup> power dissipation<sup>1</sup> @ 75°C ∆T, nat @ 1 W, @ 1 W, @ 1 W, @ 75°C ∆T, nat 400 LFM conv (°C/W) 200 LFM nat conv conv (°C/W) (°C/W) (°C/W) (W) 12.67 17.2 4.4 2.9 5.92 HSB32-232318

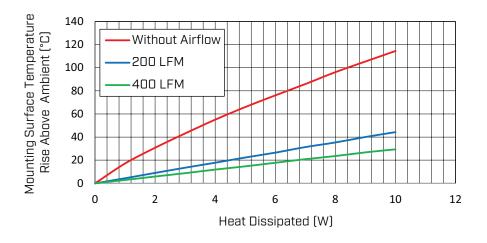
Note: 1. See performance curves for full thermal resistance details.

## PERFORMANCE CURVES

	Heatsink Temperature Rise Above Ambient (ΔT = Ths - Ta) (°C)		
Power (W)	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	17.2	4.4	2.9
2	30.8	9.0	5.9
3	43.2	13.5	8.8
4	55.1	17.8	11.9
5	66.0	22.3	14.7
6	76.1	26.5	17.8
7	85.9	31.3	20.9
8	96.2	35.3	23.6
9	105.4	40.0	26.8
10	114.5	44.2	29.4



Ta: ambient temperature

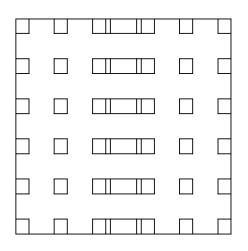


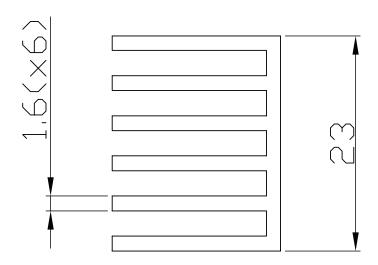
# **MECHANICAL DRAWING**

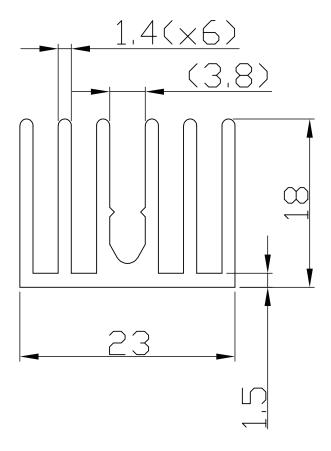
units: mm

tolerance: ±0.50 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	14 g







### **REVISION HISTORY**

rev.	description	date
1.0	initial release	03/01/2024

The revision history provided is for informational purposes only and is believed to be accurate.



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